

4

3

DRG. NO. B - 2487 SH. REF. A

Comp. Side Layer Order

0.005"	1. Signal_1
0.010"	2. Power +5V
0.010"	3. Signal_2
0.035"	4. Power GND
0.093 +/- 0.008	5. Power +2.5V
0.010"	6. Signal_3
0.005"	7. Power +3.3V
0.005"	8. Signal_4

Board Characteristics

- All dimensions are given in inches unless specified otherwise.
- Material FR4 Tg>170C.
- Minimum trace width 0.006" on all layers.
- Minimum clearance 0.006" on all layers.
- 1 oz copper for all trace and power layers.
- Ni/Au (Chem plated) over bare copper.
- Apply Solder Mask over bare copper.
- Board Thickness: 0.093 +/- 0.008
- Mill the Top and Bottom of board on the solder side to a thickness of 0.062" +/- 0.008.
- Silkscreen on Component and Solder Sides.
- 45 degree chamfer.
- FHS tolerances: +/- 0.002 unless specified otherwise.
- Interlayer spacing as specified
- Impedance : 55 Ohm +/- 5 Ohm for 0.006" traces on all layers.
- Perform TDR test using existing traces on board.

DRILL SYMBOL	FHS	COUNT	PLATED	Tolerance	COMMENT
O	.016	1068	YES	---	
⊖	.018	3627	YES	---	
⊘	.0236	114	YES	Note 12.	Note 12.
⊖	.033	312	YES	---	
⊘	.035	80	YES	---	
⊖	.041	536	YES	---	
⊘	.042	60	YES	---	
□	.057	12	YES	---	
	.09	12	NO	---	
	.106	11	NO	---	
	.113	6	NO	---	
	.16	2	YES	---	

Note 12: This is a pressfit technology thru hole with the following specification:

12-1. Finished plated hole size: 0.59 - 0.65 mm.

12-2. Drilled hole size: 0.7mm +/- 0.02mm

12-3. Thickness of thru hole plating: min. 25 μm Cu; Ni: 2.5-5 μm; Au (Chem plated): 0.05-0.2 μm.

THIS SHEET IS COMPUTER GENERATED

4

3

2

1

A

B

C

D

A

B

C

D

UNIVERSITY OF CHICAGO
ELECTRONICS DEVELOPMENT GROUP

TITLE: CDF SVT GhostBuster Board
Specification Drawing

UNLESS OTHERWISE SPECIFIED DIMENSIONS ARE IN INCHES FRACTIONS .XX DECIMALS .XX	CONTRACT NO.	APPROVALS	DATE	SCALE	SHEET
DO NOT SCALE DRAWING		PREPARED BY: M. Bogdan	5/16/01	1/4	1
		CHECKED BY: H. Sonders	5/16/01		
FINISH	ISSUED				
STANDARD					